



# 74ALVT16373

16-bit transparent D-type latch; 3-state

Rev. 7 — 25 June 2024

Product data sheet

## 1. General description

The 74ALVT16373 is a 16-bit D-type transparent latch with 3-state outputs. The device can be used as two 8-bit transparent latches or a single 16-bit transparent latch. The device features two latch enables (1LE and 2LE) and two output enables (1OE and 2OE), each controlling 8-bits. When nLE is HIGH, data at the inputs enter the latches. In this condition the latches are transparent, a latch output will change each time its corresponding D-input changes. When nLE is LOW the latches store the information that was present at the inputs a set-up time preceding the HIGH-to-LOW transition of nLE. A HIGH on nOE causes the outputs to assume a high-impedance OFF-state. Operation of the nOE input does not affect the state of the latches. Bus hold data inputs eliminate the need for external pull-up resistors to define unused inputs

## 2. Features and benefits

- Wide supply voltage range from 2.3 to 3.6 V
- Overvoltage tolerant inputs to 5.5 V
- BiCMOS high speed and output drive
- 16-bit transparent latch
- 5 V I/O compatible
- 3-state buffers
- Output capability: +64 mA/-32 mA
- Direct interface with TTL levels
- Input and output interface capability to systems at 5 V supply
- Bus-hold data inputs eliminate the need for external pull-up resistors to hold unused inputs
- Live insertion/extraction permitted
- Power-up reset
- Power-up 3-State
- No bus current loading when output is tied to 5 V bus
- I<sub>OFF</sub> circuitry provides partial Power-down mode operation
- Latch-up performance exceeds 500 mA per JESD 78 Class II Level B
- ESD protection:
  - HBM: ANSI/ESDA/JEDEC JS-001 class 2 exceeds 2000 V
  - CDM: ANSI/ESDA/JEDEC JS-002 class C3 exceeds 1000 V
- Specified from -40 °C to 85 °C

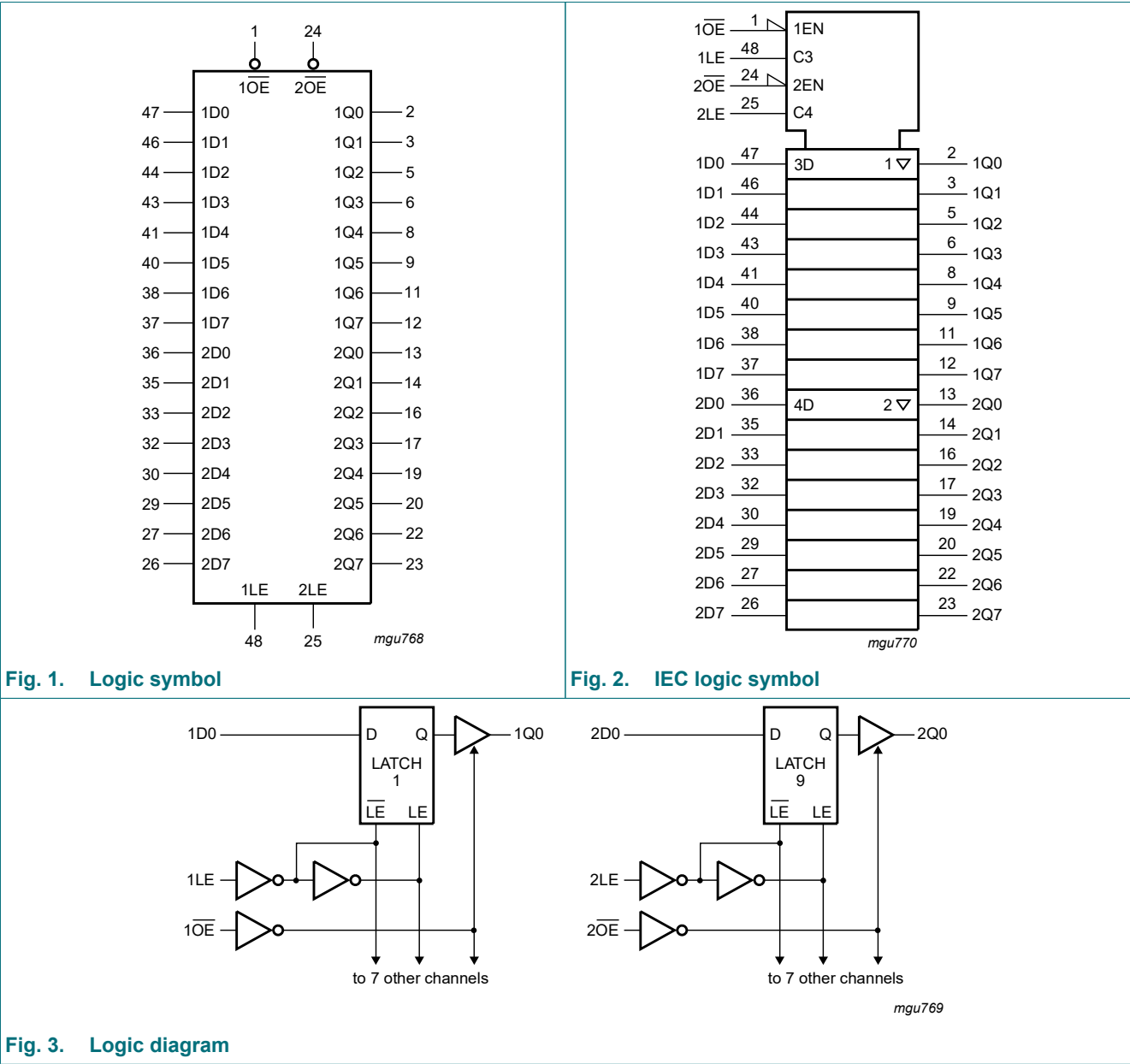
## 3. Ordering information

Table 1. Ordering information

| Type number                    | Package           |         |  |                          |
|--------------------------------|-------------------|---------|--|--------------------------|
|                                | Temperature range | Name    | Description  | Version                  |
| <a href="#">74ALVT16373DGG</a> | -40 °C to +85 °C  | TSSOP48 | plastic thin shrink small outline package; 48 leads; body width 6.1 mm | <a href="#">SOT362-1</a> |



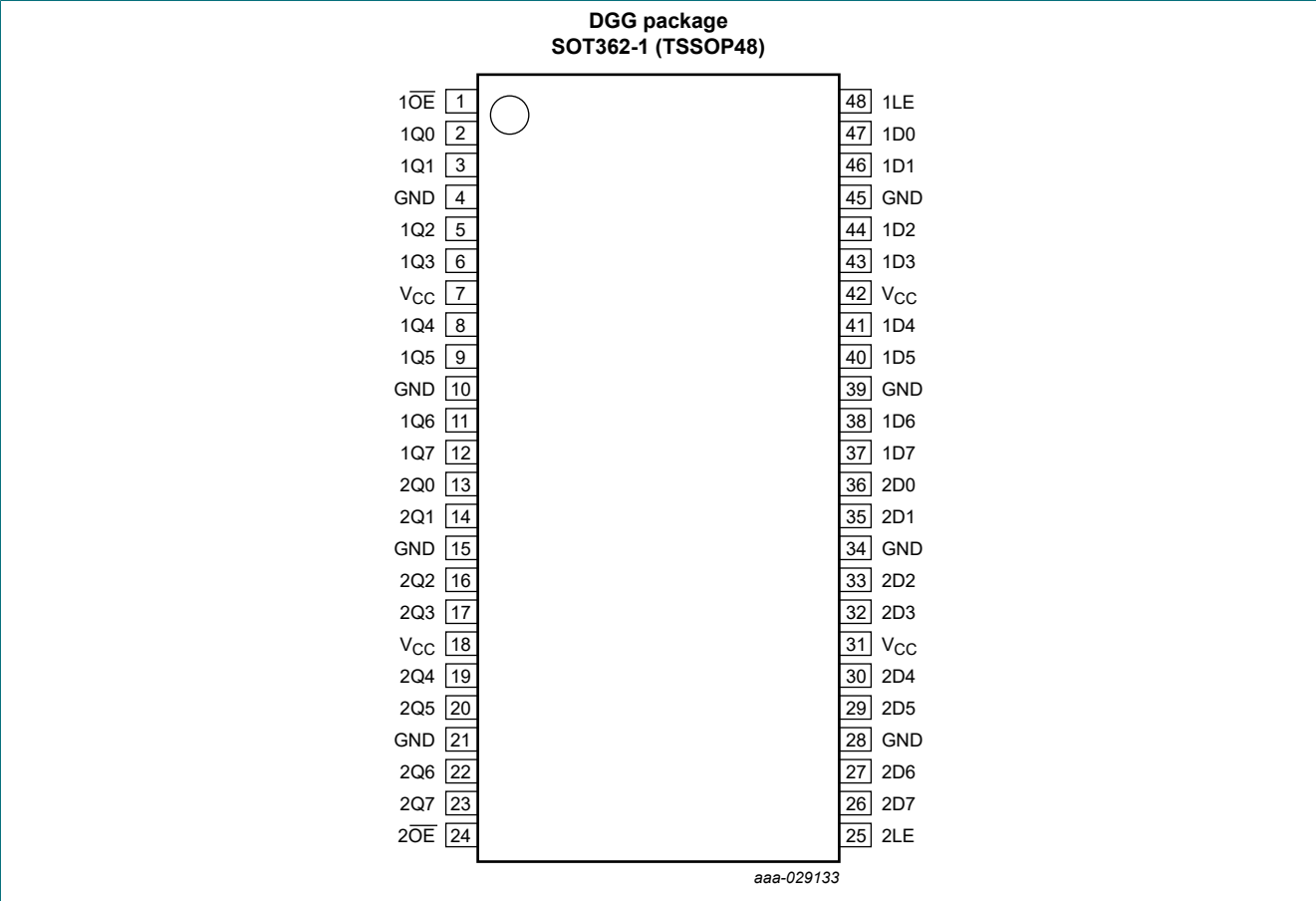
4. Functional diagram





5. Pinning information

5.1. Pinning



5.2. Pin description

Table 2. Pin description

| Symbol                                 | Pin                            | Description                       |
|--|--------------------------------|-----------------------------------|
| 1D0, 1D1, 1D2, 1D3, 1D4, 1D5, 1D6, 1D7 | 47, 46, 44, 43, 41, 40, 38, 37 | data inputs                       |
| 2D0, 2D1, 2D2, 2D3, 2D4, 2D5, 2D6, 2D7 | 36, 35, 33, 32, 30, 29, 27, 26 | data inputs                       |
| 1Q0, 1Q1, 1Q2, 1Q3, 1Q4, 1Q5, 1Q6, 1Q7 | 2, 3, 5, 6, 8, 9, 11, 12       | data outputs                      |
| 2Q0, 2Q1, 2Q2, 2Q3, 2Q4, 2Q5, 2Q6, 2Q7 | 13, 14, 16, 17, 19, 20, 22, 23 | data outputs                      |
| 1OE, 2OE                               | 1, 24                          | output enable inputs (active LOW) |
| 1LE, 2LE                               | 48, 25                         | latch enable inputs (active HIGH) |
| GND                                    | 4, 10, 15, 21, 28, 34, 39, 45  | ground (0 V)                      |
| VCC                                    | 7, 18, 31, 42                  | supply voltage                    |



6. Functional description

Table 3. Function table

H = HIGH voltage level; h = HIGH voltage level one set-up time prior to the HIGH-to-LOW LE transition;  
L = LOW voltage level; l = LOW voltage level one set-up time prior to the HIGH-to-LOW LE transition;  
↓ = HIGH-to-LOW LE transition;  
X = don't care; NC = No change; Z = high-impedance OFF-state.

| Operating mode                              | Inputs |     |     | Internal latches | Outputs nQn |
|---|--------|-----|-----|------------------|-------------|
|   | nOE    | nLE | nDn |                  |             |
| enable and read register (transparent mode) | L      | H   | L   | L                | L           |
|   | L      | H   | H   | H                | H           |
| latch and read register                     | L      | ↓   | l   | L                | L           |
|   | L      | ↓   | h   | H                | H           |
| Hold  | L      | L   | X   | NC               | NC          |
| Latch register and disable outputs          | H      | L   | X   | NC               | Z           |
|   | H      | H   | nDn | nDn              | Z           |

7. Limiting values

Table 4. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134). Voltages are referenced to GND (ground = 0 V).

| Symbol           | Parameter               | Conditions                            | Min  | Max  | Unit |
|------------------|-------------------------|---------------------------------------|------|------|------|
| V <sub>CC</sub>  | supply voltage          |                                       | -0.5 | +4.6 | V    |
| V <sub>I</sub>   | input voltage           | [1]                                   | -0.5 | +7.0 | V    |
| V <sub>O</sub>   | output voltage          | output in OFF-state or HIGH-state [1] | -0.5 | +7.0 | V    |
| I <sub>IK</sub>  | input clamping current  | V <sub>I</sub> < 0 V                  | -50  | -    | mA   |
| I <sub>OK</sub>  | output clamping current | V <sub>O</sub> < 0 V                  | -50  | -    | mA   |
| I <sub>O</sub>   | output current          | output in LOW-state                   | -    | 128  | mA   |
|                  |                         | output in HIGH-state                  | -64  | -    | mA   |
| T <sub>stg</sub> | storage temperature     |                                       | -65  | +150 | °C   |
| T <sub>j</sub>   | junction temperature    | [2]                                   | -    | +150 | °C   |

- [1] The input and output negative voltage ratings may be exceeded if the input and output clamp current ratings are observed.  
[2] The performance capability of a high-performance integrated circuit in conjunction with its thermal environment can create junction temperatures which are detrimental to reliability.



8. Recommended operating conditions

Table 5. Recommended operating conditions

| Symbol           | Parameter                           | Conditions   | V <sub>CC</sub> = 2.5 V ± 0.2 V |     | V <sub>CC</sub> = 3.3 V ± 0.3 V |     | Unit |
|------------------|-------------------------------------|--|---------------------------------|-----|---------------------------------|-----|------|
|                  |                                     |  | Min                             | Max | Min                             | Max |      |
| V <sub>CC</sub>  | supply voltage                      |  | 2.3                             | 2.7 | 3.0                             | 3.6 | V    |
| V <sub>I</sub>   | input voltage                       |  | 0                               | 5.5 | 0                               | 5.5 | V    |
| I <sub>OH</sub>  | HIGH-level output current           |  | -                               | -8  | -                               | -32 | mA   |
| I <sub>OL</sub>  | LOW-level output current            | none   | -                               | 8   | -                               | 32  | mA   |
|                  |                                     | current duty cycle ≤ 50 %;<br>f <sub>i</sub> ≥ 1 kHz | -                               | 24  | -                               | 64  | mA   |
| Δt/ΔV            | input transition rise and fall rate | outputs enabled                                      | -                               | 10  | -                               | 10  | ns/V |
| T <sub>amb</sub> | ambient temperature                 | free-air   | -40                             | +85 | -40                             | +85 | °C   |

9. Static characteristics

Table 6. Static characteristics

At recommended operating conditions; T<sub>amb</sub> = -40 °C to +85 °C; voltages are referenced to GND (ground = 0 V).

| Symbol                          | Parameter                          | Conditions   | Min                   | Typ[1] | Max  | Unit |
|---------------------------------|------------------------------------|--|-----------------------|--------|------|------|
| V <sub>CC</sub> = 2.5 V ± 0.2 V |                                    |  |                       |        |      |      |
| V <sub>IK</sub>                 | input clamping voltage             | V <sub>CC</sub> = 2.3 V; I <sub>IK</sub> = -18 mA  | -                     | -0.85  | -1.2 | V    |
| V <sub>IH</sub>                 | HIGH-level input voltage           |  | 1.7                   | -      | -    | V    |
| V <sub>IL</sub>                 | LOW-level input voltage            |  | -                     | -      | 0.7  | V    |
| V <sub>OH</sub>                 | HIGH-level output voltage          | V <sub>CC</sub> = 2.3 V to 2.7 V; I <sub>O</sub> = -100 μA   | V <sub>CC</sub> - 0.2 | -      | -    | V    |
|                                 |                                    | V <sub>CC</sub> = 2.3 V; I <sub>O</sub> = -8 mA  | 1.8                   | -      | -    | V    |
| V <sub>OL</sub>                 | LOW-level output voltage           | V <sub>CC</sub> = 2.3 V; I <sub>O</sub> = 100 μA   | -                     | 0.07   | 0.2  | V    |
|                                 |                                    | V <sub>CC</sub> = 2.3 V; I <sub>O</sub> = 24 mA  | -                     | 0.3    | 0.5  | V    |
| V <sub>OL(pu)</sub>             | power-up LOW-level output voltage  | V <sub>CC</sub> = 2.7 V; I <sub>O</sub> = 1 mA;<br>V <sub>I</sub> = V <sub>CC</sub> or GND [2]   | -                     | -      | 0.55 | V    |
| I <sub>I</sub>                  | input leakage current              | all input pins [3]   |                       |        |      |      |
|                                 |                                    | V <sub>CC</sub> = 0 V or 2.7 V; V <sub>I</sub> = 5.5 V   | -                     | 0.1    | 10   | μA   |
|                                 |                                    | control pins   |                       |        |      |      |
|                                 |                                    | V <sub>CC</sub> = 2.7 V; V <sub>I</sub> = V <sub>CC</sub> or GND   | -                     | 0.1    | ±1   | μA   |
|                                 |                                    | data pins; [3]   |                       |        |      |      |
|                                 |                                    | V <sub>CC</sub> = 2.7 V; V <sub>I</sub> = V <sub>CC</sub>  | -                     | 0.1    | 1    | μA   |
| I <sub>OFF</sub>                | power-off leakage current          | V <sub>CC</sub> = 2.7 V; V <sub>I</sub> = 0 V  | -                     | 0.1    | -5   | μA   |
|                                 |                                    | V <sub>CC</sub> = 0 V; V <sub>I</sub> or V <sub>O</sub> = 0 V to 4.5 V   | -                     | 0.1    | ±100 | μA   |
| I <sub>BHL</sub>                | bus hold LOW current               | data inputs; V <sub>CC</sub> = 2.3 V; V <sub>I</sub> = 0.7 V [4]   | -                     | 90     | -    | μA   |
| I <sub>BHH</sub>                | bus hold HIGH current              | data inputs; V <sub>CC</sub> = 2.3 V; V <sub>I</sub> = 1.7 V [4]   | -                     | -10    | -    | μA   |
| I <sub>EX</sub>                 | external current                   | output in HIGH-state when V <sub>O</sub> > V <sub>CC</sub> ;<br>V <sub>O</sub> = 5.5 V; V <sub>CC</sub> = 2.3 V                        | -                     | 10     | 125  | μA   |
| I <sub>O(pu/pd)</sub>           | power-up/power-down output current | V <sub>CC</sub> ≤ 1.2 V; V <sub>O</sub> = 0.5 V to V <sub>CC</sub> ;<br>V <sub>I</sub> = GND or V <sub>CC</sub> ; nOE = don't care [5] | -                     | 1      | 100  | μA   |



| Symbol   | Parameter                          | Conditions  | Min            | Typ[1]   | Max       | Unit          |
|--|------------------------------------|---|----------------|----------|-----------|---------------|
| $I_{OZ}$   | OFF-state output current           | $V_{CC} = 2.7 \text{ V}$ ; $V_I = V_{IL}$ or $V_{IH}$   |                |          |           |               |
|  |                                    | output HIGH: $V_O = 2.3 \text{ V}$  | -              | 0.5      | 5         | $\mu\text{A}$ |
|  |                                    | output LOW: $V_O = 0.5 \text{ V}$   | -              | 0.5      | -5        | $\mu\text{A}$ |
| $I_{CC}$   | supply current                     | $V_{CC} = 2.7 \text{ V}$ ; $V_I = \text{GND}$ or $V_{CC}$ ; $I_O = 0 \text{ A}$   |                |          |           |               |
|  |                                    | outputs HIGH  | -              | 0.04     | 0.1       | $\text{mA}$   |
|  |                                    | outputs LOW   | -              | 2.3      | 4.5       | $\text{mA}$   |
|  |                                    | outputs disabled [6]  | -              | 0.04     | 0.1       | $\text{mA}$   |
| $\Delta I_{CC}$  | additional supply current          | per input pin; $V_{CC} = 2.3 \text{ V}$ to $2.7 \text{ V}$ ;<br>one input at $V_{CC} - 0.6 \text{ V}$ ;<br>other inputs at $V_{CC}$ or $\text{GND}$ [7] | -              | 0.04     | 0.4       | $\text{mA}$   |
| $C_I$  | input capacitance                  | $V_I = 0 \text{ V}$ or $V_{CC}$   | -              | 3        | -         | $\text{pF}$   |
| $C_O$  | output capacitance                 | Outputs disabled; $V_O = 0 \text{ V}$ or $3 \text{ V}$  | -              | 9        | -         | $\text{pF}$   |
| <b><math>V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}</math></b> |                                    |   |                |          |           |               |
| $V_{IK}$   | input clamping voltage             | $V_{CC} = 3.0 \text{ V}$ ; $I_{IK} = -18 \text{ mA}$  | -              | -0.85    | -1.2      | $\text{V}$    |
| $V_{IH}$   | HIGH-level input voltage           |   | 2.0            | -        | -         | $\text{V}$    |
| $V_{IL}$   | LOW-level input voltage            |   | -              | -        | 0.8       | $\text{V}$    |
| $V_{OH}$   | HIGH-level output voltage          | $V_{CC} = 3.3 \text{ V} \pm 0.3 \text{ V}$ ; $I_O = -100 \mu\text{A}$   | $V_{CC} - 0.2$ | $V_{CC}$ | -         | $\text{V}$    |
|  |                                    | $V_{CC} = 3.0 \text{ V}$ ; $I_O = -32 \text{ mA}$   | 2.0            | 2.3      | -         | $\text{V}$    |
| $V_{OL}$   | LOW-level output voltage           | $V_{CC} = 3.0 \text{ V}$ ; $I_O = 100 \mu\text{A}$  | -              | 0.07     | 0.2       | $\text{V}$    |
|  |                                    | $V_{CC} = 3.0 \text{ V}$ ; $I_O = 16 \text{ mA}$  | -              | 0.25     | 0.4       | $\text{V}$    |
|  |                                    | $V_{CC} = 3.0 \text{ V}$ ; $I_O = 32 \text{ mA}$  | -              | 0.3      | 0.5       | $\text{V}$    |
|  |                                    | $V_{CC} = 3.0 \text{ V}$ ; $I_O = 64 \text{ mA}$  | -              | 0.4      | 0.55      | $\text{V}$    |
| $V_{OL(pu)}$   | power-up LOW-level output voltage  | $V_{CC} = 3.6 \text{ V}$ ; $I_O = 1 \text{ mA}$ ;<br>$V_I = V_{CC}$ or $\text{GND}$ [2]   | -              | -        | 0.55      | $\text{V}$    |
| $I_I$  | input leakage current              | all input pins [3]  |                |          |           |               |
|  |                                    | $V_{CC} = 0 \text{ V}$ or $3.6 \text{ V}$ ; $V_I = 5.5 \text{ V}$   | -              | 0.1      | 10        | $\mu\text{A}$ |
|  |                                    | control pins  |                |          |           |               |
|  |                                    | $V_{CC} = 3.6 \text{ V}$ ; $V_I = V_{CC}$ or $\text{GND}$   | -              | 0.1      | $\pm 1$   | $\mu\text{A}$ |
|  |                                    | data pins [3]   |                |          |           |               |
|  |                                    | $V_{CC} = 3.6 \text{ V}$ ; $V_I = V_{CC}$   | -              | 0.5      | 1         | $\mu\text{A}$ |
|  |                                    | $V_{CC} = 3.6 \text{ V}$ ; $V_I = 0 \text{ V}$  | -              | 0.1      | -5        | $\mu\text{A}$ |
| $I_{OFF}$  | power-off leakage current          | $V_{CC} = 0 \text{ V}$ ; $V_I$ or $V_O = 0 \text{ V}$ to $4.5 \text{ V}$  | -              | 0.1      | $\pm 100$ | $\mu\text{A}$ |
| $I_{BHL}$  | bus hold LOW current               | data inputs; $V_{CC} = 3 \text{ V}$ ; $V_I = 0.8 \text{ V}$   | 75             | 130      | -         | $\mu\text{A}$ |
| $I_{BHH}$  | bus hold HIGH current              | data inputs; $V_{CC} = 3 \text{ V}$ ; $V_I = 2.0 \text{ V}$   | -75            | -140     | -         | $\mu\text{A}$ |
| $I_{BHLO}$   | bus hold LOW overdrive current     | data inputs; $V_{CC} = 3.6 \text{ V}$ ;<br>$V_I = 0 \text{ V}$ to $3.6 \text{ V}$ [8]   | 500            | -        | -         | $\mu\text{A}$ |
| $I_{BHHO}$   | bus hold HIGH overdrive current    | data inputs; $V_{CC} = 3.6 \text{ V}$ ;<br>$V_I = 0 \text{ V}$ to $3.6 \text{ V}$ [8]   | -500           | -        | -         | $\mu\text{A}$ |
| $I_{EX}$   | external current                   | output in HIGH-state when $V_O > V_{CC}$ ;<br>$V_O = 5.5 \text{ V}$ ; $V_{CC} = 3.0 \text{ V}$  | -              | 10       | 125       | $\mu\text{A}$ |
| $I_{O(pu/pd)}$   | power-up/power-down output current | $V_{CC} \leq 1.2 \text{ V}$ ; $V_O = 0.5 \text{ V}$ to $V_{CC}$ ;<br>$V_I = \text{GND}$ or $V_{CC}$ ; $nOE = \text{don't care}$ [9]                     | -              | 1        | $\pm 100$ | $\mu\text{A}$ |
| $I_{OZ}$   | OFF-state output current           | $V_{CC} = 3.6 \text{ V}$ ; $V_I = V_{IL}$ or $V_{IH}$   |                |          |           |               |
|  |                                    | output HIGH: $V_O = 3.0 \text{ V}$  | -              | 0.5      | 5         | $\mu\text{A}$ |
|  |                                    | output LOW: $V_O = 0.5 \text{ V}$   | -              | 0.5      | -5        | $\mu\text{A}$ |



| Symbol           | Parameter                 | Conditions  | Min | Typ[1] | Max | Unit |
|------------------|---------------------------|---|-----|--------|-----|------|
| I <sub>CC</sub>  | supply current            | V <sub>CC</sub> = 3.6 V; V <sub>I</sub> = GND or V <sub>CC</sub> ; I <sub>O</sub> = 0 A   |     |        |     |      |
|                  |                           | outputs HIGH  | -   | 0.04   | 0.1 | mA   |
|                  |                           | outputs LOW   | -   | 3.5    | 5   | mA   |
|                  |                           | outputs disabled [6]  | -   | 0.05   | 0.1 | mA   |
| ΔI <sub>CC</sub> | additional supply current | per input pin; V <sub>CC</sub> = 3 V to 3.6 V;<br>one input at V <sub>CC</sub> - 0.6 V;<br>other inputs at V <sub>CC</sub> or GND [7] | -   | 0.04   | 0.4 | mA   |
| C <sub>I</sub>   | input capacitance         | V <sub>I</sub> = 0 V or V <sub>CC</sub>   | -   | 3      | -   | pF   |
| C <sub>O</sub>   | output capacitance        | output disabled; V <sub>O</sub> = 0 V or 3 V  | -   | 9      | -   | pF   |

- [1] All typical values for V<sub>CC</sub> = 2.5 V ± 0.2 V are measured at V<sub>CC</sub> = 2.5 V and T<sub>amb</sub> = 25 °C.  
All typical values for V<sub>CC</sub> = 3.3 V ± 0.3 V are measured at V<sub>CC</sub> = 3.3 V and T<sub>amb</sub> = 25 °C.
- [2] For valid test results, data must not be loaded into the latches after applying power.
- [3] Unused pins at V<sub>CC</sub> or GND.
- [4] Not guaranteed.
- [5] This parameter is valid for any V<sub>CC</sub> between 0 V and 1.2 V with a transition time of up to 10 ms.  
From V<sub>CC</sub> = 1.2 V to V<sub>CC</sub> = 2.5 V ± 0.2 V a transition time of 100 μs is permitted. This parameter is valid for T<sub>amb</sub> = 25 °C only.
- [6] I<sub>CC</sub> with outputs disabled is measured with outputs pulled to V<sub>CC</sub> or GND.
- [7] This is the increase in supply current for each input at the specified voltage level other than V<sub>CC</sub> or GND.
- [8] This is the bus hold overdrive current required to force the input to the opposite logic state.
- [9] This parameter is valid for any V<sub>CC</sub> between 0 V and 1.2 V with a transition time of up to 10 ms.  
From V<sub>CC</sub> = 1.2 V to V<sub>CC</sub> = 3.3 V ± 0.3 V a transition time of 100 μs is permitted. This parameter is valid for T<sub>amb</sub> = 25 °C only.

10. Dynamic characteristics

Table 7. Dynamic characteristics

At recommended operating conditions; T<sub>amb</sub> = -40 °C to +85 °C; voltages are referenced to GND (ground = 0 V);  
for test circuit see Fig. 8.

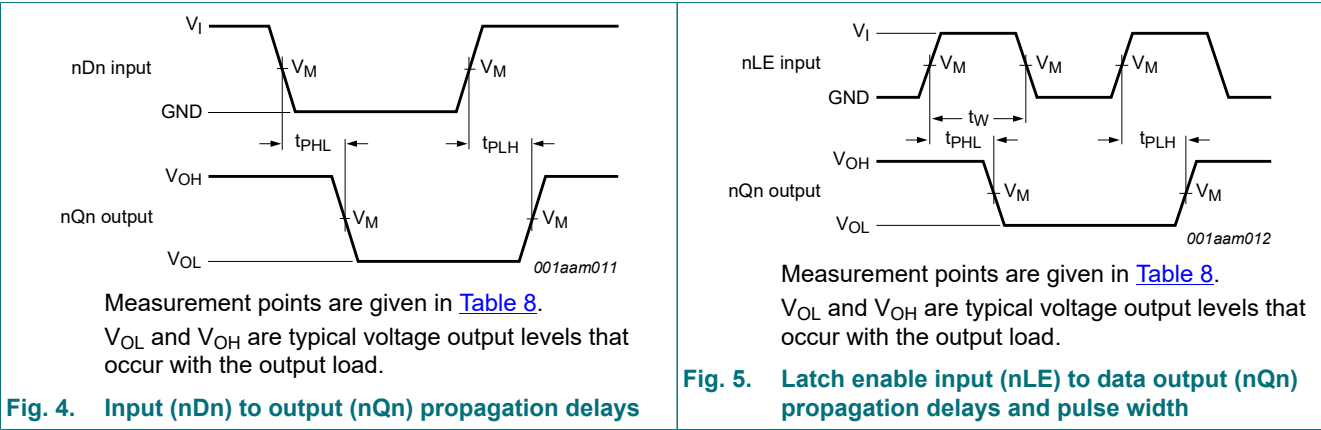
| Symbol                          | Parameter                           | Conditions             | Min | Typ[1] | Max | Unit |
|---------------------------------|-------------------------------------|------------------------|-----|--------|-----|------|
| V <sub>CC</sub> = 2.5 V ± 0.2 V |                                     |                        |     |        |     |      |
| t <sub>PLH</sub>                | LOW to HIGH propagation delay       | nDn to nQn; see Fig. 4 | 1.0 | 2.0    | 3.2 | ns   |
| t <sub>PHL</sub>                | HIGH to LOW propagation delay       | nDn to nQn; see Fig. 4 | 1.0 | 2.4    | 4.2 | ns   |
| t <sub>PLH</sub>                | LOW to HIGH propagation delay       | nLE to nQn; see Fig. 5 | 1.5 | 2.6    | 4.2 | ns   |
| t <sub>PHL</sub>                | HIGH to LOW propagation delay       | nLE to nQn; see Fig. 5 | 1.5 | 2.8    | 4.5 | ns   |
| t <sub>PZH</sub>                | OFF-state to HIGH propagation delay | nOE to nQn; see Fig. 6 | 2.0 | 3.5    | 5.5 | ns   |
| t <sub>PZL</sub>                | OFF-state to LOW propagation delay  | nOE to nQn; see Fig. 6 | 1.5 | 2.6    | 4.7 | ns   |
| t <sub>PHZ</sub>                | HIGH to OFF-state propagation delay | nOE to nQn; see Fig. 6 | 1.5 | 2.7    | 4.5 | ns   |
| t <sub>PLZ</sub>                | LOW to OFF-state propagation delay  | nOE to nQn; see Fig. 6 | 1.0 | 2.0    | 3.5 | ns   |
| t <sub>su(H)</sub>              | set-up time HIGH                    | nDn to nLE; see Fig. 7 | 0   | -0.7   | -   | ns   |
| t <sub>su(L)</sub>              | set-up time LOW                     | nDn to nLE; see Fig. 7 | 1.5 | 0.2    | -   | ns   |
| t <sub>h(H)</sub>               | hold time HIGH                      | nDn to nLE; see Fig. 7 | 0.5 | -0.2   | -   | ns   |
| t <sub>h(L)</sub>               | hold time LOW                       | nDn to nLE; see Fig. 7 | 1.5 | 0.7    | -   | ns   |
| t <sub>WH</sub>                 | pulse width HIGH                    | nLE; see Fig. 5        | 1.5 | -      | -   | ns   |



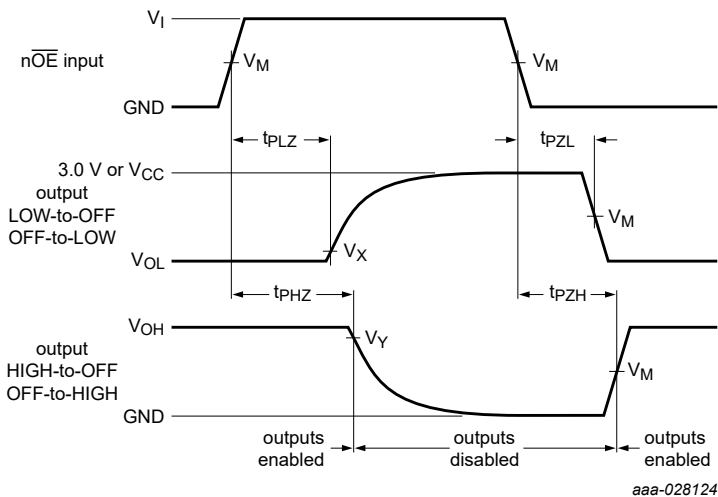
| Symbol                                | Parameter                           | Conditions                           | Min | Typ[1] | Max | Unit |
|---------------------------------------|-------------------------------------|--------------------------------------|-----|--------|-----|------|
| <b>V<sub>CC</sub> = 3.3 V ± 0.3 V</b> |                                     |                                      |     |        |     |      |
| t <sub>PLH</sub>                      | LOW to HIGH propagation delay       | nDn to nQn; see Fig. 4               | 0.5 | 1.6    | 2.5 | ns   |
| t <sub>PHL</sub>                      | HIGH to LOW propagation delay       | nDn to nQn; see Fig. 4               | 0.5 | 1.8    | 2.9 | ns   |
| t <sub>PLH</sub>                      | LOW to HIGH propagation delay       | nLE to nQn; see Fig. 5               | 1.0 | 2.0    | 3.1 | ns   |
| t <sub>PHL</sub>                      | HIGH to LOW propagation delay       | nLE to nQn; see Fig. 5               | 1.0 | 2.3    | 3.3 | ns   |
| t <sub>PZH</sub>                      | OFF-state to HIGH propagation delay | n $\overline{OE}$ to nQn; see Fig. 6 | 1.5 | 2.3    | 4.0 | ns   |
| t <sub>PZL</sub>                      | OFF-state to LOW propagation delay  | n $\overline{OE}$ to nQn; see Fig. 6 | 1.0 | 1.9    | 3.1 | ns   |
| t <sub>PHZ</sub>                      | HIGH to OFF-state propagation delay | n $\overline{OE}$ to nQn; see Fig. 6 | 1.5 | 2.9    | 4.5 | ns   |
| t <sub>PLZ</sub>                      | LOW to OFF-state propagation delay  | n $\overline{OE}$ to nQn; see Fig. 6 | 1.5 | 2.3    | 3.7 | ns   |
| t <sub>su(H)</sub>                    | set-up time HIGH                    | nDn to nLE; see Fig. 7               | 0.5 | -0.2   | -   | ns   |
| t <sub>su(L)</sub>                    | set-up time LOW                     | nDn to nLE; see Fig. 7               | 0.8 | 0.2    | -   | ns   |
| t <sub>h(H)</sub>                     | hold time HIGH                      | nDn to nLE; see Fig. 7               | 0.8 | 0      | -   | ns   |
| t <sub>h(L)</sub>                     | hold time LOW                       | nDn to nLE; see Fig. 7               | 1.0 | 0.2    | -   | ns   |
| t <sub>WH</sub>                       | pulse width HIGH                    | nLE; see Fig. 5                      | 1.5 | -      | -   | ns   |

[1] All typical values for V<sub>CC</sub> = 2.5 V ± 0.2 V are measured at V<sub>CC</sub> = 2.5 V and T<sub>amb</sub> = 25 °C.  
All typical values for V<sub>CC</sub> = 3.3 V ± 0.3 V are measured at V<sub>CC</sub> = 3.3 V and T<sub>amb</sub> = 25 °C.

10.1. Waveforms and test circuit

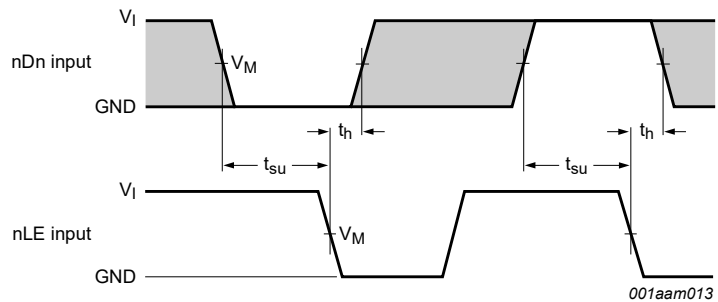






Measurement points are given in [Table 8](#).  
 $V_{OL}$  and  $V_{OH}$  are typical voltage output levels that occur with the output load.

**Fig. 6. OFF-state to HIGH or LOW and HIGH or LOW to OFF-state propagation delays**



Measurement points are given in [Table 8](#).

**Fig. 7. Input (nDn) to input (nLE) data set-up and hold times**

**Table 8. Measurement points**

| $V_{CC}$                   | Input          |                | Output         |                          |                          |
|----------------------------|----------------|----------------|----------------|--------------------------|--------------------------|
|                            | $V_I$          | $V_M$          | $V_M$          | $V_X$                    | $V_Y$                    |
| $V_{CC} \leq 2.7\text{ V}$ | $V_{CC}$       | $0.5V_{CC}$    | $0.5V_{CC}$    | $V_{OL} + 0.15\text{ V}$ | $V_{OH} - 0.15\text{ V}$ |
| $V_{CC} \geq 3.0\text{ V}$ | $3.0\text{ V}$ | $1.5\text{ V}$ | $1.5\text{ V}$ | $V_{OL} + 0.3\text{ V}$  | $V_{OH} - 0.3\text{ V}$  |



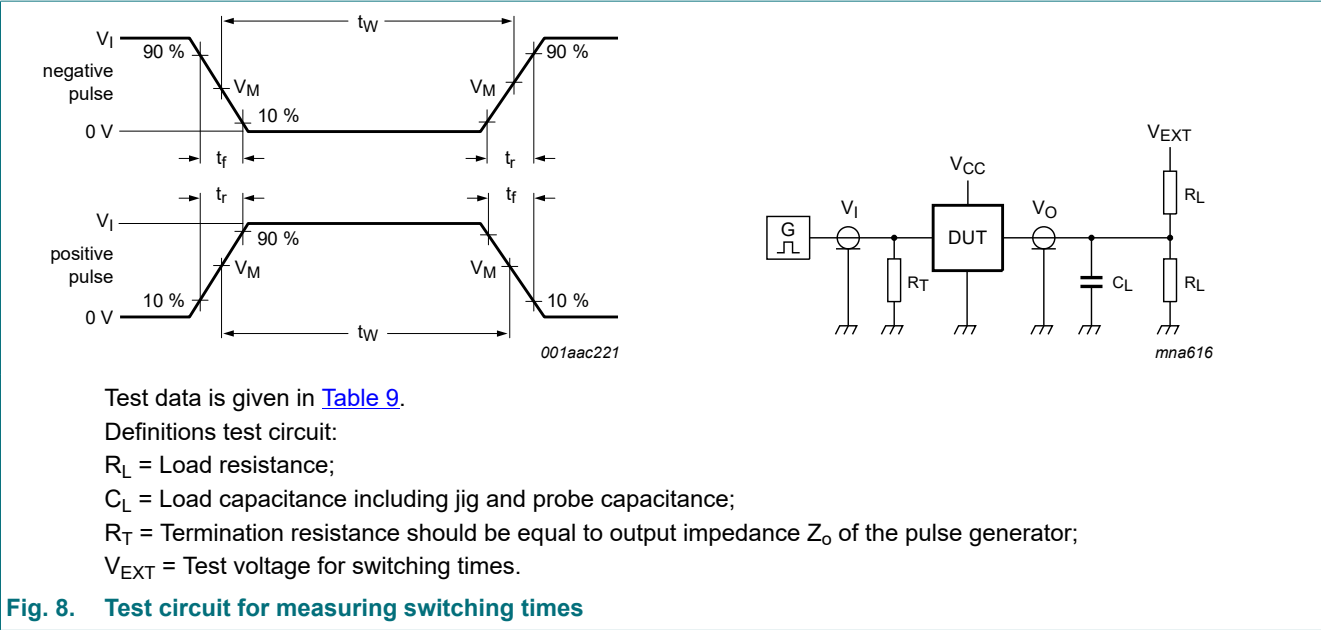


Table 9. Test data

| Input                               |               |        |               | Load  |              | $V_{EXT}$          |                    |                    |
|-------------------------------------|---------------|--------|---------------|-------|--------------|--------------------|--------------------|--------------------|
| $V_I$                               | $f_i$         | $t_W$  | $t_r, t_f$    | $C_L$ | $R_L$        | $t_{PHZ}, t_{PZH}$ | $t_{PLZ}, t_{PZL}$ | $t_{PLH}, t_{PHL}$ |
| 3.0 V or $V_{CC}$ whichever is less | $\leq 10$ MHz | 500 ns | $\leq 2.5$ ns | 50 pF | 500 $\Omega$ | GND                | 6 V or $2V_{CC}$   | open               |



11. Package outline

TSSOP48: plastic thin shrink small outline package; 48 leads; body width 6.1 mm SOT362-1

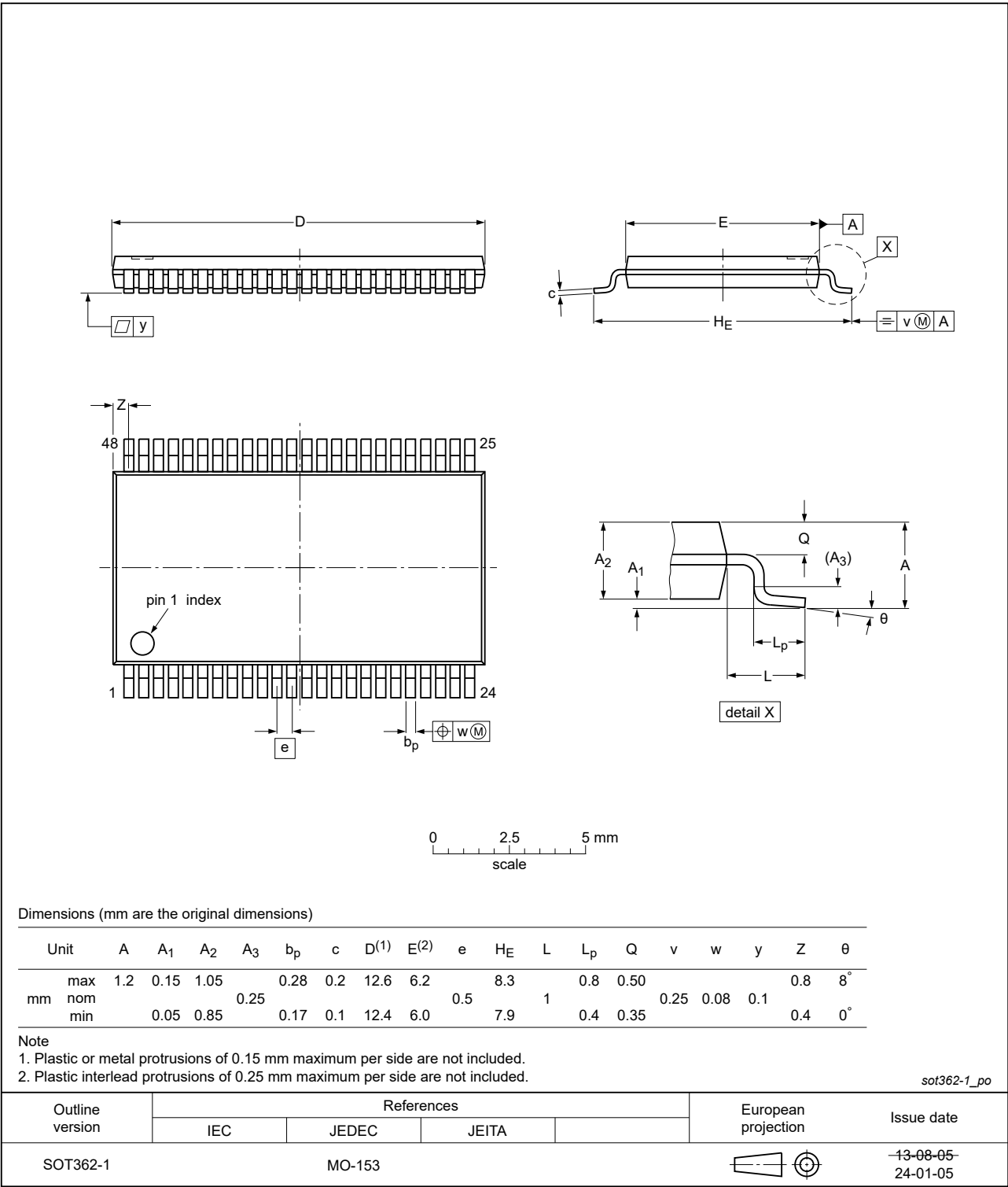


Fig. 9. Package outline SOT362-1 (TSSOP48)



12. Abbreviations

Table 10. Abbreviations

| Acronym | Description                                     |
|---------|---|
| ANSI    | American National Standards Institute           |
| BiCMOS  | Bipolar Complementary Metal Oxide Semiconductor |
| CDM     | Charged Device Model                            |
| DUT     | Device Under Test                               |
| ESD     | ElectroStatic Discharge                         |
| ESDA    | ElectroStatic Discharge Association             |
| HBM     | Human Body Model                                |
| JEDEC   | Joint Electron Device Engineering Council       |
| TTL     | Transistor-Transistor Logic                     |

13. Revision history

Table 11. Revision history

| Document ID     | Release date   | Data sheet status     | Change notice | Supersedes      |
|-----------------|--|-----------------------|---------------|-----------------|
| 74ALVT16373 v.7 | 20240625   | Product data sheet    | -             | 74ALVT16373 v.6 |
| Modifications:  | <ul style="list-style-type: none"><li><a href="#">Section 2</a>: ESD specification updated according to the latest JEDEC standard.</li></ul>   |                       |               |                 |
| 74ALVT16373 v.6 | 20240425   | Product data sheet    | -             | 74ALVT16373 v.5 |
| Modifications:  | <ul style="list-style-type: none"><li><a href="#">Fig. 9</a>: Updated package outline drawing SOT362-1 (TSSOP48).</li></ul>  |                       |               |                 |
| 74ALVT16373 v.5 | 20210714   | Product data sheet    | -             | 74ALVT16373 v.4 |
| Modifications:  | <ul style="list-style-type: none"><li><a href="#">Section 1</a> and <a href="#">Section 2</a> updated.</li><li>Type number 74ALVT16373DL (SOT370-1/SSOP48) removed.</li></ul>  |                       |               |                 |
| 74ALVT16373 v.4 | 20180202   | Product data sheet    | -             | 74ALVT16373 v.3 |
| Modifications:  | <ul style="list-style-type: none"><li>The format of this data sheet has been redesigned to comply with the identity guidelines of Nexperia.</li><li>Legal texts have been adapted to the new company name where appropriate.</li></ul> |                       |               |                 |
| 74ALVT16373 v.3 | 19991018   | Product specification | -             | 74ALVT16373 v.2 |
| 74ALVT16373 v.2 | 19980213   | Product specification | -             | 74ALVT16373 v.1 |
| 74ALVT16373 v.1 | 19960529   | Product specification | -             | -               |



## 14. Legal information

### Data sheet status

| Document status [1][2]         | Product status [3] | Definition  |
|--------------------------------|--------------------|---|
| Objective [short] data sheet   | Development        | This document contains data from the objective specification for product development. |
| Preliminary [short] data sheet | Qualification      | This document contains data from the preliminary specification.                       |
| Product [short] data sheet     | Production         | This document contains the product specification.                                     |

- [1] Please consult the most recently issued document before initiating or completing a design.
- [2] The term 'short data sheet' is explained in section "Definitions".
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Contents

1. General description..... 1

2. Features and benefits..... 1

3. Ordering information..... 1

4. Functional diagram..... 2

5. Pinning information..... 3

5.1. Pinning..... 3

5.2. Pin description..... 3

6. Functional description..... 4

7. Limiting values..... 4

8. Recommended operating conditions..... 5

9. Static characteristics..... 5

10. Dynamic characteristics..... 7

10.1. Waveforms and test circuit..... 8

11. Package outline..... 11

12. Abbreviations..... 12

13. Revision history..... 12

14. Legal information..... 13

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